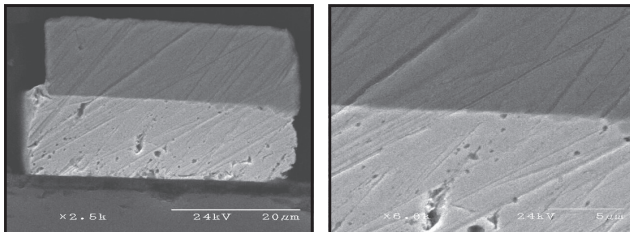
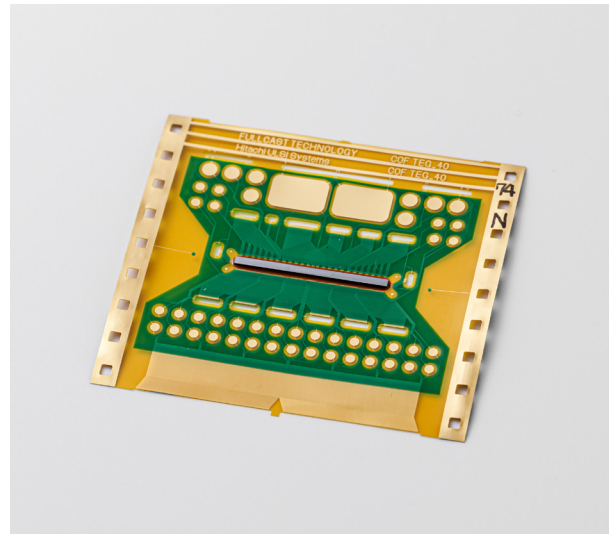
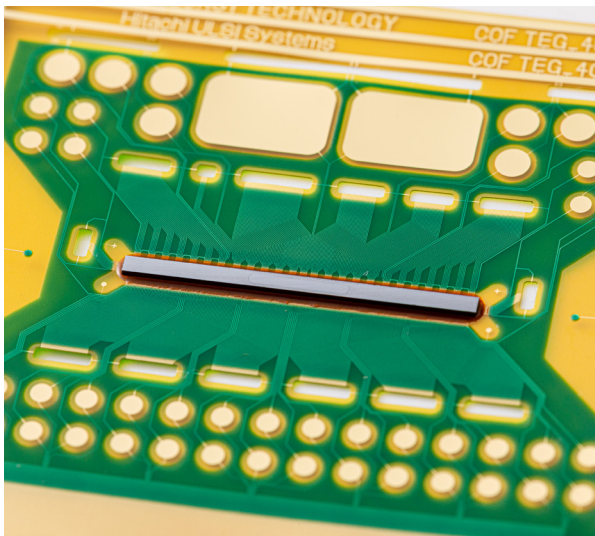




# Bonding ボンディング

## フリップチップ接合

半導体／多バンプ電極音波接合



(Magnified bonded cross section)

Chip size: 20.05×1.06×0.42 mm  
 Chip bump: Au plated 770 pins  
 Bump pitch: 40 (30) μm  
 Substrate: Au plated pads on 2 layers of film

### Product used 使用する装置

▶ サウンド&ヒートボンダ



AP-J-0083A4-2025040301